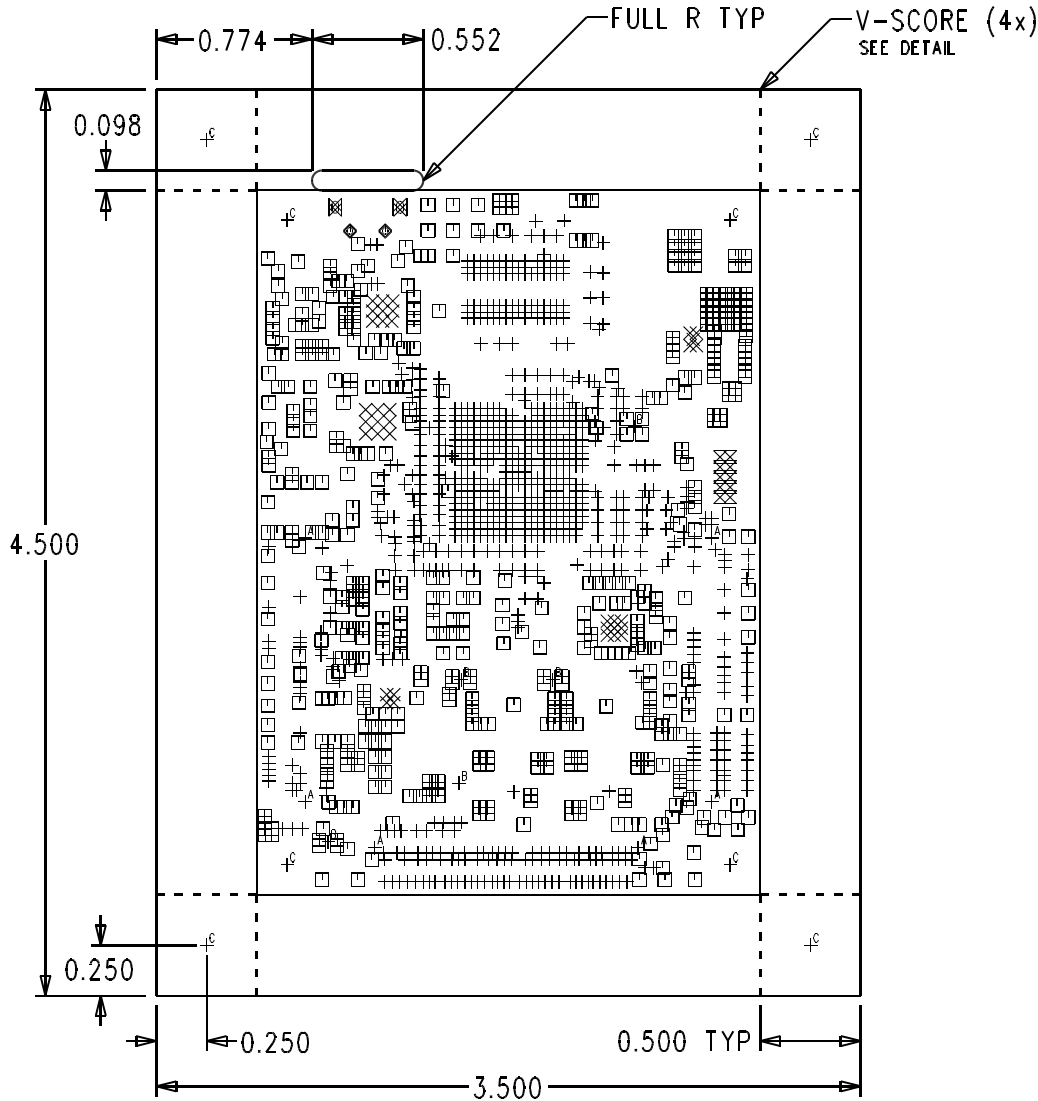


REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
A	NEW RELEASE	C.C.D.	03/12/20	
B	UPDATED PER ECO	C.C.D.	12/11/20	

SIZE	QTY	SYM	PLATED	TOL
0.006	890	+	YES	+0.003/-0.006
0.0119	36	×	YES	+0.003/-0.0119
0.012	536	□	YES	+0.003/-0.012
0.026 x 0.033	2	◇	YES	+/-0.003
0.029	10	⊠	YES	+/-0.003
0.033 x 0.059	2	⊠	YES	+/-0.003
0.033	6	† ^A	NO	+/-0.003
0.04	5	† ^B	YES	+/-0.003
0.125	8	† ^C	NO	+/-0.005

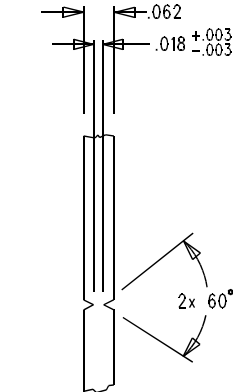
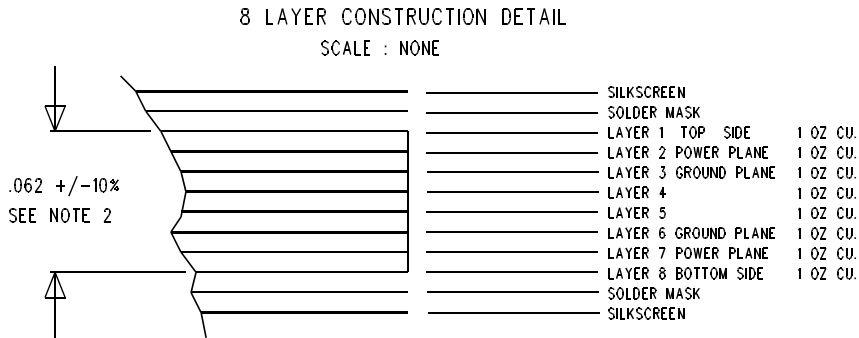


UNLESS OTHERWISE SPECIFIED


- BOARD TO BE FABRICATED PER IPC-6012A, CLASS 2.
- MATERIAL: POLYCLAD FR4 OR EQUIVALENT. VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
- PLATING: ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND. MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE PER IPC-6012A WITH AMENDMENT 1, CLASS 2 REQUIREMENTS. WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
- FINISH: SURFACES TO BE COATED BY ENIG OF 2 TO 10 MICROINCHES OVER A MINIMUM OF 60-200 MICROINCHES OF LOW STRESS NICKEL.
- SOLDERMASK: SOLDER MASK TO BE TRANSPARENT BLUE LPI BOTH SIDES PER GERBER FILES.
- SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
- ARTWORK: MINIMUM FEATURE SIZE = 0.0035
MINIMUM AIR GAP = 0.004
- ALL DIMENSIONS ARE IN INCHES. EXCEPT FOR BOARD OUTLINE DIMENSIONS
- CONTROLLED IMPEDANCE: SEE CHART
- THIEVING IS ALLOWED, UNLESS OTHERWISE SPECIFIED.
- VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS. METHOD 1 IS PREFERRED.
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES BOTH SIDES.
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
- VIA HOLES (.006, .0119, .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
- TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
- REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 4 AND 5 IS ACCEPTABLE.
- USE IPC-D-356 NETLIST AS SUPPLIED FOR CHECKING.
- ALL .0119 DRILLS ARE VIA-IN-PAD. THESE DRILLS TO BE FILLED AND PLATED.

LAYER	50 S/E	100 D/P WIDTH/SPACE	90 D/P WIDTH/SPACE
1 SIG	.0055	-----	.00525/.00475
2 PLN			
3 PLN			
4 SIG	.0055	.003/.007	-----
5 SIG	.0055	.003/.007	-----
6 PLN			
7 PLN			
8 SIG	.0055	.005/.006	.00525/.00475

IMPEDANCE CHART
ALL IMPEDANCES +/-5%



SCORING DETAIL
4 PLACES

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		 2 Elizabeth Drive Chelmsford, MA 01824	
	APPROVALS	DATE		
MATERIAL SEE NOTES	DRAWN C.C.D.	12/11/20	FABRICATION DRAWING EV-21569-SOM	
	CHECKED			
FINISH SEE NOTES	ENGINEERING		SIZE B	DWG. NO. EV-21569-SOM_PCB
	QUALITY			
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE 1 : 1	SHEET 1 OF 1